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[TITLE OF THE INVENTION]

EPOXY RESIN COMPOSITIONS AND THEIR LOW DIELECTRIC CURED MATERIALS THEREOF

[0063]

(As the aromatic carboxylic acid for improving heat resistance,) tricarboxylic acid such as trimesic acid or acid anhydride thereof and acid chloride thereof; tetracarboxylic acid such as pyromellitic acid, 3,3,4,4-biphenyl tetracarboxylic acid or acid anhydride thereof; naphthalene dicarboxylic acid such as 1,4-naphthalene dicarboxylic acid, 2,6-naphthalene dicarboxylic acid, 2,3-naphthalene dicarboxylic acid or acid anhydride thereof; and 3,3,4,4-benzophenone tetracarboxylic acid or acid anhydride thereof are exemplified.

As the aromatic compound having a phenolic hydroxyl group, phenols such as phenol, cresol, and xlenol; benzene diols such as hydroquinone, resorcin, catechol, and methylhydroquinone; benzene triols such as phloroglucin,

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naphthols such as α -naphthol and β -naphthol; naphthalene diols, biphenols such as o-phenyl phenol, 2,2-dihydroxy biphenyl, 2,2,4,4-tetramethylbiphenol and 2,2,4,4-tetrahydroxy benzophenone are exemplified.